TOSHIBA 1SS357

TOSHIBA DIODE SILICON EPITAXIAL SCHOTTKY BARRIER TYPE

1 S S 3 5 7

LOW VOLTAGE HIGH SPEED SWITCHING.

Low Forward Voltage : $V_{F(3)} = 0.54 \text{ (Typ.)}$

Low Resistance Current : $I_R = 5\mu A$ (Max.)

Small Package : SC-70

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	SYMBOL RATING		
Maximum (Peak) Reverse Voltage	$v_{ m RM}$	85	V	
Reverse Voltage	$V_{\mathbf{R}}$	80	V	
Maximum (Peak) Forward Current	$I_{ extbf{FM}}$	200	mA	
Average Forward Current	IO	100	mA	
Surge Current (10ms)	$I_{ ext{FSM}}$	1	Α	
Power Dissipation	P	200*	mW	
Junction Temperature	T_{j}	125	°C	
Storage Temperature Range	${ m T_{stg}}$	-55~125	°C	

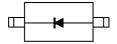
Unit in mm 1. $25^{+0.2}_{-0.1}$ 0 ± 0.05 0. $15^{+0.1}_{-0.06}$ **JEDEC EIAJ** TOSHIBA 1-1E1A

Weight: 0.004g

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	V _{F (1)}	I _F =1mA	_	0.28		
	$V_{F(2)}$	$I_{\mathbf{F}} = 10 \text{mA}$	1	0.36	_	V
	$V_{F(3)}$	$I_{ m F} = 100 { m mA}$		0.54	0.60	
Reverse Current	$I_{\mathbf{R}}$	$V_R = 40V$	_	_	5	μ A
Total Capacitance	C_{T}	$V_R=0V$, $f=1MHz$	_	18	25	pF

(TOP VIEW)



Marking



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Mounted on a glass epoxy circuit board of 20×20mm, pad dimension of 4×4mm.

